Can additive manufacturing (AM) be used to manufacture a low cost, high efficiency primary heat exchanger (HX) for Concentrating Solar Power (CSP)?

**BACKGROUND**

CSP can provide clean, dispatchable power, overcoming the grid integration challenges faced by photovoltaics and wind power. To be cost competitive, CSP must use high efficiency power cycles (i.e., supercritical carbon dioxide (sCO2) Brayton cycle). Currently, the primary HX accounts for 60-70% of cost for this cycle. Reducing HX cost is critical for increasing CSP adoption. This requires unconventional designs, materials, and manufacturing techniques to meet demanding operating requirements.

- > 50% thermal efficiency
- > 700 °C temperature, 200 bar pressure
- Highly corrosive environment

AM via Laser powder bed fusion (LPBF) builds parts layer-by-layer with resolutions of a few hundred micrometers. AM (LPBF) offers several advantages for HX design:

- Use of difficult to machine materials
- Complex, compact, flexible geometrical design
- Elimination of welded joints

**INTEGRATED DESIGN PROCESS**

- Mech. design of pin structure
- Design optimization/parametric analysis
- Correlation-based model for thermal design
- Detailed conjugate CFD of “unit”
- Dimensional Tolerance & Surface Measurement
- Thermal + mechanical stress analysis
- Fatigue & Creep analysis
- Select Material
- Rapid Prototype
- Establish Print Parameters
- Process Based Cost Modeling
- Cost reduction pathways are modeled to determine if AM cost reduction would be possible. Design and manufacturing process optimization could reduce HX cost from $780/kW to $430/kW. Innovations in AM machines could further reduce HX cost from $430/kW to $270/kW. Recently, a new machine was announced by SLM that will enable many of these cost reductions to be realized.

Haynes 230 (H230), which has long been used in high temperature applications, is a good candidate for the primary CSP HX. Since H230 is not widely used in AM, successful printing required:

- Calibrating machine parameters to produce fully dense components
- Adjusting design to achieve dimensional tolerance of fine features
- Demonstrating the mechanical and corrosion performance of AM H230 is comparable to wrought H230

**AM PROCESS DEVELOPMENT & PROTOTYPE**

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**INITIAL MODULAR HX DESIGN & COST**

**CONCLUSIONS**

- Established parameters to print fully dense H230 using AM
- Demonstrated good high temperature mechanical performance and corrosion resistance in printed H230
- Successfully printed prototype HX
- Showed design and process optimization with near term AM technology upgrades can lower AM HX cost.

Future Work

- Switch to more creep resistant Haynes 282 for design flexibility
- Optimize cost – performance tradeoff

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